

22. (Unchanged) The substrate processing system according to claim 20 wherein the dielectric film is to be deposited over a plurality of stepped surfaces formed on the substrate having gaps formed between adjacent ones of the stepped surfaces and wherein the first portion of the film partially fills the gaps.

This application is a Divisional Patent Application of Appl. No. 09/648,395 filed August 24, 2000 ("the parent application"). On June 5, 2001, Claims 17-22 were subjected to an oral restriction requirement by the Examiner and were withdrawn when Applicant's representative elected Claims 1-16. Accordingly, Claims 17-22 are presented in this Divisional Application.

Since no amendments have been made to individual claims - Claims 17-22 are presented in the same form as in the parent application and there are no new claims - no Appendix is provided to highlight changes made to the claims.

In view of the foregoing, Applicants believe all claims now pending in this Application are in condition for allowance. The issuance of a formal Notice of Allowance at an early date is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 303-571-4000.

Respectfully submitted,



Patrick M. Boucher  
Reg. No. 44,037

TOWNSEND and TOWNSEND and CREW LLP  
Two Embarcadero Center, 8<sup>th</sup> Floor  
San Francisco, California 94111-3834  
Tel: (303) 571-4000  
Fax: (303) 571-4321  
PMB:nlm

DE 7046901 v1

T02030 T030200